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(57) Abstract

An EMI/RFI shielded cover plate assembly for an electronics enclosure (10) includes a cover plate (18; 20) having a major surface area (24) with outwardly-projecting walls or flanges defining interface locations with the underlying enclosure. A shielding compound (22) is provided across the entire cover plate (18; 20) including the walls (25) or flanges. The shielding compound (22) is disposed in a relatively thin layer across the major surface area (24) of the cover plate (18; 20) for EMI/RFI shielding, and in a thicker layer at the interface locations (25; 27) to provide a gasket-like response for environmentally sealing the cover plate (18; 20) assembly to the underlying enclosure and for thermal transfer and electrical continuity. The shielding compound (22) can be compression molded with the cover plate (18; 20). The shielded cover plate assembly provides a simple and economical method for providing an EMI/RFI shield and a gasket from a single shielding compound.

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